

U.S. Patent Application Serial No. 09/889,587  
Amendment dated September 8, 2003  
Reply to OA of June 10, 2003

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

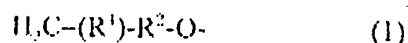
Claim 1 (currently amended): A curable resin composition comprising:

(I) a reactive silicon group-containing polyoxyalkylene polymer wherein an introduction ratio of a reactive silicon group into molecular chain termini, defined as the percentage of the termini into which the reactive silicon group has been introduced based on the total number of molecular chain termini, is not less than [90%] 95% as determined by <sup>1</sup>H-NMR analysis, and

(II) an epoxy resin.

Claim 2 (previously presented): The curable resin composition according to Claim 1

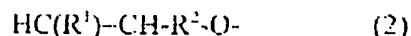
wherein the reactive silicon group-containing polyoxyalkylene polymer (I) is obtained by reacting (a) a polyoxylalkylene polymer terminating in an unsaturated group of either the general formula (I):



in the formula R<sup>1</sup> represents a hydrocarbon group containing not more than 10 carbon atoms; R<sup>2</sup> represents a divalent organic group containing 1 to 20 carbon atoms which contains one or more members selected from the group consisting of hydrogen, oxygen and nitrogen as the constituent atoms,

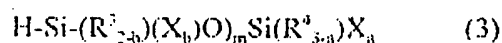
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or the general formula (2):



in the formula  $R^1$  represents a hydrocarbon group containing not more than 10 carbon atoms;  $R^2$  represents a divalent organic group containing 1 to 20 carbon atoms which contains one or more members selected from the group consisting of hydrogen, oxygen and nitrogen as the constituent atoms,

with (b) a reactive silicon group-containing compound of the general formula (3):



in the formula  $R^3$  and  $R^4$  each represents an alkyl group containing 1 to 20 carbon atoms, an aryl group containing 6 to 20 carbon atoms, an aralkyl group containing 7 to 20 carbon atoms, or a triorganosiloxy group of the formula  $(\text{R}^*)_3\text{SiO-}$ ; when two or more  $R^3$  or  $R^4$  groups are present, they may be the same or different;  $R^1$  represents a univalent hydrocarbon group of 1 to 20 carbon atoms; the three of  $R^*$  groups may be the same or different;  $X$  represents a hydroxyl group or a hydrolyzable group; when two or more  $X$  groups are present, they may be the same or different;  $a$  represents 0, 1, 2 or 3;  $b$  represents 0, 1 or 2;  $b$  may be the same or different over  $m$  repeats of  $-\text{Si(R}^3_{2-b})(\text{X}_b)_m\text{-O-}$ ;  $m$  represents an integer of 0 through 19; provided, however, that the condition of  $a + \sum b \geq 1$  is satisfied,

(c) in the presence of a Group VIII transition metal catalyst.

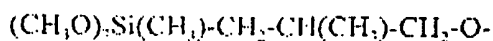
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Claim 3 (original): The curable resin composition according to Claim 1 or 2

wherein a reactive silicon group-containing molecular chain terminus of the reactive silicon group-containing polyoxyalkylene polymer (I) is represented by the following formula;



Claim 4 (previously presented): The curable resin composition according to Claim 1 or 2

comprising a compound having both a functional group capable of reacting with an epoxy group and a reactive silicon group

or a compound having both an epoxy group and a reactive silicon group.

Claim 5 (new): The curable resin composition according to Claim 1

wherein the introduction ratio of a reactive silicon group into molecular chain termini is not less than 98%.